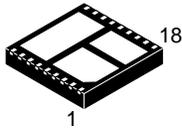


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

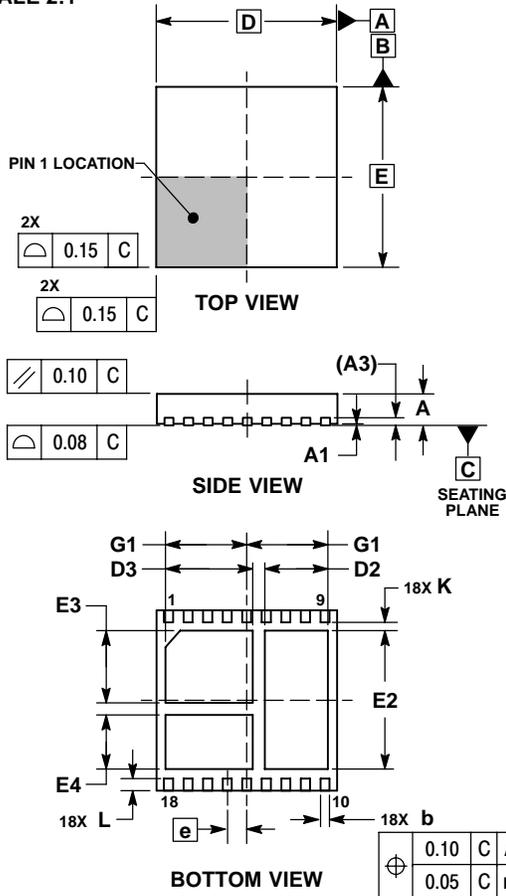
ON Semiconductor®



SCALE 2:1

DFN18
CASE 506BD-01
ISSUE O

DATE 06 SEP 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	0.90
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
D	6.00 BSC	
D2	2.05	2.15
D3	2.85	2.95
E	6.00 BSC	
E2	4.55	4.65
E3	2.35	2.45
E4	1.80	1.90
e	0.65 BSC	
G1	2.65	2.75
K	0.20 MIN	
L	0.35	0.45

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	18 PIN DFN, 6X6 MM. 0.65 MM PITCH	PAGE 1 OF 2

